

ABSTRACT

The present invention relates to a substrate polishing apparatus for polishing a substrate, such as a wafer, and more particularly to a substrate polishing apparatus for polishing a notch of a substrate, a bevel portion of the substrate, a device surface of the substrate, and a back surface of the substrate. The substrate polishing apparatus includes: a first polishing module; a second polishing module; and a third polishing module; wherein the first polishing module, the second polishing module, and the third polishing module are configured to polish different regions of a substrate.

FIG. 1